

Application No. 09/830253  
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Amendment

serigraphy.

12. (New) Method as claimed in claim 10, wherein the soldering cream (8) is deposited by syringe.

13. (New) Method as claimed in claim 10, the circuit having a ground plane, wherein it makes it possible to produce an electromagnetic shield integrated directly into the electronic module by conducting connections (19)(21) to the ground plane (20) of the circuit (3).

14. (New) Method as claimed in claim 10, wherein it makes it possible to integrate as close to the connecting balls (7) as possible and on the same side of the electronic module decoupling capacitors (17) and/or serial resistors (16) and/or filtering cells and/or quartz adapter condensers.

15. (New) Method as claimed in claims 10, wherein the side of the module opposite the side comprising the balls and the components allows gripping of the module by suction.

16. (New) A gripping and collective transfer device (9) for balls (7) or geometrically identical preforms, comprising a working face (11) whose configuration is adapted to the dimensions and to the volume of the balls or preforms to be gripped, such that it is possible to avoid any contact with the electronic components (2) or any other obstacle that might be present on the surface (12) of a substrate (1).

17. (New) Device as claimed in claim 16, wherein the gripping device (9) is equipped with a vacuum chamber (13) into which open all of the orifices for holding the balls or preforms (7) in order to seize and place all of said balls simultaneously.

18. (New) Device as claimed in claim 7, wherein the working face (11) of the gripping device (9) defining the face for holding the balls or preforms (7) is adapted to the dimensions of these balls or preforms and to the shape of a receiver substrate (12).

19. (New) Method as claimed in claim 10, the module being directly connectable by soldering to the printed circuit.

20. (New) Method as claimed in claim 10, wherein the interconnection or shielding balls have a diameter greater than the height of said components.